

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HYUNG JONG CHOI	04/19/2021
YOO JEONG LEE	04/19/2021
KWAN YOUNG SON	04/19/2021
WOO KYUNG SUNG	04/19/2021
KYU SIK PARK	04/19/2021
MYUNG JUN PARK	04/19/2021
KWANG YEUN WON	04/19/2021
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City:	SUWON-SI, GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17470251
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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NAME OF SUBMITTER:	SANDRA JOHNSON
SIGNATURE:	/Sandra Johnson/
DATE SIGNED:	09/10/2021
Total Attachments: 3	

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Title of
Invention

DECLARATION

This declaration
is directed to:

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ASSIGNMENT

[illegible]

other relevant treaties;

I hereby authorize and request the United States Patent and Trademark Office and officials in patent offices in foreign countries to issue any and all of said Letters Patent to the ASSIGNEE as the assignee of my entire right, title, and interest in and to the same, for the sole use and benefit of the ASSIGNEE, and its lawful successors and assigns, to the full end of the term for which said Letters Patent may be granted;

I hereby grant the attorney of record the power to insert on this Assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office or other authority for recordation of this document;

I hereby covenant that I have the full right to convey the interest assigned by this Assignment, and I have not executed and will not execute any agreement in conflict with this Assignment; and

Further, I hereby further covenant and agree that I will, without further consideration, communicate with the ASSIGNEE, and its lawful successors and assigns, any facts known to me respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said ASSIGNEE, and its lawful successors or assigns, execute all divisional, continuation, continuation-in-part, and reissue applications, make all rightful oaths and generally do everything possible to aid the ASSIGNEE, and its lawful successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the ASSIGNEE, and its lawful successors and assigns.

IN TESTIMONY WHEREOF, I have hereunto set my hands.

NAME OF INVENTOR (Full Legal Name) : Hyung Jong CHOI

Signature: _____

Date: 2021-04-19

NAME OF INVENTOR (Full Legal Name) : Yoo Jeong LEE

Signature: _____

Date: 2021-04-19

NAME OF INVENTOR (Full Legal Name) : Kwan Young SON

Signature: _____

Date: 2021-04-19

NAME OF INVENTOR (Full Legal Name) : Woo Kyung SUNG

Signature: _____

Date: 2021-04-19

NAME OF INVENTOR (Full Legal Name) : Kyu Sik PARK

Signature: _____

Date: 2021-04-19

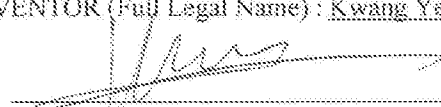
NAME OF INVENTOR (Full Legal Name) : Myung Jun PARK

Signature: _____

Date: 2021-04-19

Morgan, Lewis & Bockius LLP

NAME OF INVENTOR (Full Legal Name) : Kwang Yeun WON

Signature: 

Date: 2021-4-19

SAMSUNG

HYUNGJONG.CHOI

Morgan, Lewis & Bockius LLP